

Product Change Notification / NTDO-30AGGY971

Date:

04-Feb-2022

Product Category:

SONET/SDH/T1/E1 Devices

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4701 Final Notice: Qualification of ATK as an additional assembly site for Microsemi PM4390-FEI, PM5338-FEI, and PM5337-FEI catalog part numbers (CPN) available in 896L BBGA (31x31x3.32mm) package.

Affected CPNs:

NTDO-30AGGY971_Affected_CPN_02042022.pdf NTDO-30AGGY971_Affected_CPN_02042022.csv

Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of ATK as an additional assembly site for Microsemi PM4390-FEI, PM5338-FEI, and PM5337-FEI catalog part numbers (CPN) available in 896L BBGA (31x31x3.32mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change							
Assembly Site	Stats Chippac Korea Ltd. (STAK)	Stats Chippac Korea Ltd. (STAK)	d. Amkor Technology Korea (K4), INC (ATK)						
Substrate core material	E679FGBR	E679FGBR	E705G						
SM Material	AUS703	AUS703	AUS703						
Substrate Process	ABF	ABF	GX92						
Bump Material	Sn1.8Ag	Sn1.8Ag	Sn1.8Ag						
Die Attach Epoxy	WF3617	WF3617	SCF5						
Underfill Material	U8410-73C	U8410-73C	NAU-27-1F						
Solder ball Flux	WF6063M5	WF6063M5	SCF-3						
Thermal Grease	SE4450	SE4450	DCL-5						
Heat Spreader	R011-0208X	R011-0208X	101334107						
Solder Ball Material	SAC305	SAC305	SAC305						

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve productivity by qualifying ATK as an additional assembly site for Microsemi PM4390-FEI, PM5338-FEI, and PM5337-FEI catalog part numbers (CPN).

Change Implementation Status: In Progress

Estimated First Ship Date:November 15, 2021 (date code: 2147)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	June 2021				October 2021				November 2021						February 2022							
Workwee k	2 3	2 4	2 5	2 6	2 7	>	4 0	4 1	4 2	4 3	4 4	4 5	4 6	4 7	4 8	4 9	>	0 6	0 7	0 8	0 9	1 0
Initial PCN Issue Date			Х																			
Qual Report Availabilit y																		Х				
Final PCN Issue Date										Х												

Estimated First Ship Date

Method to Identify Change:

Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 14, 2021: Issued initial notification. October 22, 2021: Issued final notification. Provided an estimated first ship date to be on November 15, 2021.

February 04, **2022**: Re-issued final notification. Attached qualification report and updated the timetable summary.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_NTDO-30AGGY971_Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. NTDO-30AGGY971 - CCB 4701 Final Notice: Qualification of ATK as an additional assembly site for Microsemi PM4390-FEI, PM5338-FEI, and PM5337-FEI catalog part numbers (CPN) available in 896L BBGA (31x31x3.32mm) package.

Affected Catalog Part Numbers (CPN)

PM4390-FEI PM5338-FEI PM5337-FEI